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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3456
Number of Logic Elements/Cells	15552
Total RAM Bits	294912
Number of I/O	512
Number of Gates	985882
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	680-LBGA Exposed Pad
Supplier Device Package	680-FTEBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv600e-7fg680c

Table 1: **Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

In addition to the CLK and CE control signals, the three flip-flops share a Set/Reset (SR). For each flip-flop, this signal can be independently configured as a synchronous Set, a synchronous Reset, an asynchronous Preset, or an asynchronous Clear.

The output buffer and all of the IOB control signals have independent polarity controls.

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. After configuration, clamping diodes are connected to V_{CCO} with the exception of LVCMOS18, LVCMOS25, GTL, GTL+, LVDS, and LVPECL.

Optional pull-up, pull-down and weak-keeper circuits are attached to each pad. Prior to configuration all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive, but I/Os can optionally be pulled up.

The activation of pull-up resistors prior to configuration is controlled on a global basis by the configuration mode pins. If the pull-up resistors are not activated, all the pins are in a high-impedance state. Consequently, external pull-up or pull-down resistors must be provided on pins required to be at a well-defined logic level prior to configuration.

All Virtex-E IOBs support IEEE 1149.1-compatible Boundary Scan testing.

Input Path

The Virtex-E IOB input path routes the input signal directly to internal logic and/ or through an optional input flip-flop.

An optional delay element at the D-input of this flip-flop eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the FPGA, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signalling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

There are optional pull-up and pull-down resistors at each user I/O input for use after configuration. Their value is in the range 50 – 100 kΩ.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output signal can be routed to the buffer directly from the internal logic or through an optional IOB output flip-flop.

The 3-state control of the output can also be routed directly from the internal logic or through a flip-flip that provides synchronous enable and disable.

Each output driver can be individually programmed for a wide range of low-voltage signalling standards. Each output buffer can source up to 24 mA and sink up to 48 mA. Drive strength and slew rate controls minimize bus transients.

In most signalling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

An optional weak-keeper circuit is connected to each output. When selected, the circuit monitors the voltage on the pad and weakly drives the pin High or Low to match the input signal. If the pin is connected to a multiple-source signal, the weak keeper holds the signal in its last state if all drivers are disabled. Maintaining a valid logic level in this way eliminates bus chatter.

Since the weak-keeper circuit uses the IOB input buffer to monitor the input level, an appropriate V_{REF} voltage must be provided if the signalling standard requires one. The provision of this voltage must comply with the I/O banking rules.

I/O Banking

Some of the I/O standards described above require V_{CCO} and/or V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOBs, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

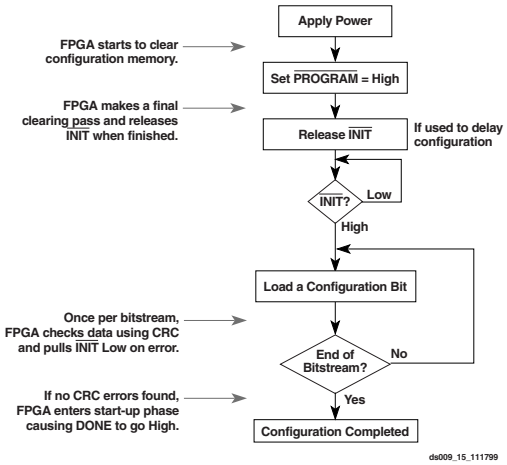

Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

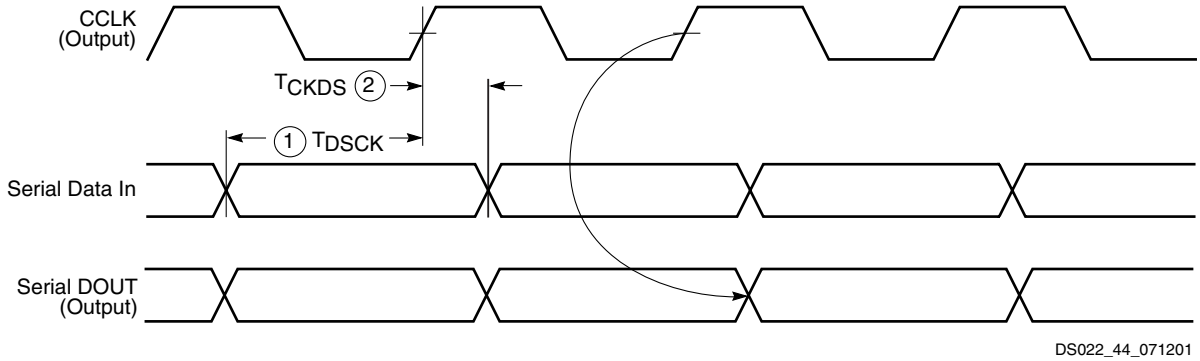

Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling $\overline{\text{PROGRAM}}$ Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select ($\overline{\text{CS}}$) signal and a Write signal ($\overline{\text{WRITE}}$). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If $\overline{\text{WRITE}}$ is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, $\overline{\text{WRITE}}$, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the $\overline{\text{CS}}$ pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of $\overline{\text{CS}}$, illustrated in Figure 17.

1. Assert $\overline{\text{WRITE}}$ and $\overline{\text{CS}}$ Low. Note that when $\overline{\text{CS}}$ is asserted on successive CCLKs, $\overline{\text{WRITE}}$ must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while $\overline{\text{CS}}$ is Low and $\overline{\text{WRITE}}$ is High. Similarly, while $\overline{\text{WRITE}}$ is High, no more that one $\overline{\text{CS}}$ should be asserted.

Verilog Initialization Example

```
module MYMEM (CLK, WE, ADDR, DIN, DOUT);
input CLK, WE;
input [8:0] ADDR;
input [7:0] DIN;
output [7:0] DOUT;

wire logic0, logic1;

//synopsys dc_script_begin
//set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
//set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
//synopsys dc_script_end

assign logic0 = 1'b0;
assign logic1 = 1'b1;

RAMB4_S8 ram0 (.WE(WE), .EN(logic1), .RST(logic0), .CLK(CLK), .ADDR(ADDR), .DI(DIN),
.DO(DOUT));
//synopsys translate_off
defparam ram0.INIT_00 =
256h'0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF;
defparam ram0.INIT_01 =
256h'FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210;
//synopsys translate_on
endmodule
```

Using SelectI/O

The Virtex-E FPGA series includes a highly configurable, high-performance I/O resource, called SelectI/O™ to provide support for a wide variety of I/O standards. The SelectI/O resource is a robust set of features including programmable control of output drive strength, slew rate, and input delay and hold time. Taking advantage of the flexibility and SelectI/O features and the design considerations described in this document can improve and simplify system level design.

Introduction

As FPGAs continue to grow in size and capacity, the larger and more complex systems designed for them demand an increased variety of I/O standards. Furthermore, as system clock speeds continue to increase, the need for high performance I/O becomes more important.

While chip-to-chip delays have an increasingly substantial impact on overall system speed, the task of achieving the desired system performance becomes more difficult with the proliferation of low-voltage I/O standards. SelectI/O, the revolutionary input/output resources of Virtex-E devices, resolve this potential problem by providing a highly configurable, high-performance alternative to the I/O resources of more conventional programmable devices. Virtex-E SelectI/O features combine the flexibility and time-to-market advantages of programmable logic with the high performance previously available only with ASICs and custom ICs.

Each SelectI/O block can support up to 20 I/O standards. Supporting such a variety of I/O standards allows the support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory buses.

SelectI/O blocks also provide selectable output drive strengths and programmable slew rates for the LVTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak “keeper” circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Virtex-E SelectI/O features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the SelectI/O features, system-level design and board design can be greatly simplified and improved.

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the global clock buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUFG connection has a net connected to it. Since the N-side IBUFG does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_p_external, O=>clk_internal);

gclk0_n : IBUFG_LVDS port map
(I=>clk_n_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_p_external),
.O(clk_internal));

IBUFG_LVDS gclk0_n (.I(clk_n_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_p_external LOC = GCLKPAD3;

NET clk_n_external LOC = C17;
```

GCLKPAD3 can also be replaced with the package pin name, such as D17 for the BG432 package.

Creating LVDS Input Buffers

An LVDS input buffer can be placed in a wide number of IOB locations. The exact location is dependent on the package that is used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side where # is the pair number.

HDL Instantiation

Only one input buffer is required to be instantiated in the design and placed on the correct IO_L#P location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location. In the physical device, a configuration option is enabled that routes the pad wire from the IO_L#N IOB to the differential input buffer located in the IO_L#P IOB. The output of this buffer then drives the output of the IO_L#P cell or the input register in the IO_L#P IOB. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map (I=>data(0),
O=>data_int(0));
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data[0]),
.O(data_int[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data<0> LOC = D28; # IO_L0P
```

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the input buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUF connection has a net connected to it. Since the N-side IBUF does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map
(I=>data_p(0), O=>data_int(0));

data0_n : IBUF_LVDS port map
(I=>data_n(0), O=>open);
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data_p[0]),
.O(data_int[0]));

IBUF_LVDS data0_n (.I(data_n[0]), .O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Adding an Input Register

All LVDS buffers can have an input register in the IOB. The input register is in the P-side IOB only. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries available to explicitly create these structures. The input library macros are listed in Table 42. The I and IB inputs to the macros are the external net connections.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
CTT	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.4	V_{REF} + 0.4	8	–8
AGP	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:
1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on www.xilinx.com.

LVDS DC Specifications

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.375	2.5	2.625	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.25	1.425	1.6	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.9	1.075	1.25	V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	250	350	450	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.25	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25 V	100	350	NA	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.2	1.25	2.2	V

Note: Refer to the Design Consideration section for termination schematics.

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under **LVPECL**, with a 100 Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	3.0		3.3		3.6		V
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3	-	0.3	-	0.3	-	V

Table 2: **IOB Input Switching Characteristics *(Continued)***

Description[2]	Symbol	Device	Speed Grade[1] Min	-8	-7	-6	Units
Sequential Delays							
Clock CLK							
Minimum Pulse Width, High	T_{CH}	All	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T_{CL}		0.56	1.2	1.3	1.4	ns, min
Clock CLK to output IQ	T_{IOCKIQ}		0.18	0.4	0.7	0.7	ns, max
Setup and Hold Times with respect to Clock at IOB Input Register							
Pad, no delay	T_{IOPICK}/ T_{IOICKP}	All	0.69 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
Pad, with delay	$T_{IOPICKD}$/ $T_{IOICKPD}$	XCV50E	1.25 / 0	2.8 / 0	2.9 / 0	2.9 / 0	ns, min
		XCV100E	1.25 / 0	2.8 / 0	2.9 / 0	2.9 / 0	ns, min
		XCV200E	1.33 / 0	3.0 / 0	3.1 / 0	3.1 / 0	ns, min
		XCV300E	1.33 / 0	3.0 / 0	3.1 / 0	3.1 / 0	ns, min
		XCV400E	1.37 / 0	3.1 / 0	3.2 / 0	3.2 / 0	ns, min
		XCV600E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
		XCV1000E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
		XCV1600E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV2000E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV2600E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
		XCV3200E	1.53 / 0	3.5 / 0	3.6 / 0	3.6 / 0	ns, min
ICE input	$T_{IOICECK}$/ $T_{IOCKICE}$	All	0.28 / 0.0	0.55 / 0.01	0.7 / 0.01	0.7 / 0.01	ns, min
SR input (IFF, synchronous)	$T_{IOSRCKI}$	All	0.38	0.8	0.9	1.0	ns, min
Set/Reset Delays							
SR input to IQ (asynchronous)	T_{IOSRIQ}	All	0.54	1.1	1.2	1.4	ns, max
GSR to output IQ	T_{GSRQ}	All	3.88	7.6	8.5	9.7	ns, max

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.
2. Input timing i for LVTTL is measured at 1.4 V. For other I/O standards, see Table 4.

Virtex-E Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *with* DLL

Description[1]	Symbol	Device	Speed Grade[2, 3]				Units
			Min	-8	-7	-6	
LVTTL Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *with* DLL. For data *output* with different standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 10.	$T_{ICKOFDLL}$	XCV50E	1.0	3.1	3.1	3.1	ns
		XCV100E	1.0	3.1	3.1	3.1	ns
		XCV200E	1.0	3.1	3.1	3.1	ns
		XCV300E	1.0	3.1	3.1	3.1	ns
		XCV400E	1.0	3.1	3.1	3.1	ns
		XCV600E	1.0	3.1	3.1	3.1	ns
		XCV1000E	1.0	3.1	3.1	3.1	ns
		XCV1600E	1.0	3.1	3.1	3.1	ns
		XCV2000E	1.0	3.1	3.1	3.1	ns
		XCV2600E	1.0	3.1	3.1	3.1	ns
		XCV3200E	1.0	3.1	3.1	3.1	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load. For other I/O standards and different loads, see Table 3 and Table 4.
3. DLL output jitter is already included in the timing calculation.

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
0	IO	C15
0	IO	B15[1]
0	IO_LVDS_DLL_L9N	A15
0	GCK3	D14
1	GCK2	B14
1	IO_LVDS_DLL_L9P	A13
1	IO	B13[1]
1	IO_L10N	C13
1	IO_L10P	A12
1	IO_L11N_Y	B12
1	IO_VREF_1_L11P_Y	C12
1	IO_L12N_Y	A11
1	IO_L12P_Y	B11
1	IO	B10[1]
1	IO_L13N	C11
1	IO_L13P	D11
1	IO	A9[1]
1	IO_L14N_YY	B9
1	IO_L14P_YY	C10
1	IO_L15N_YY	B8
1	IO_VREF_1_L15P_YY	C9
1	IO_L16N _Y	D9
1	IO_L16P _Y	A7
1	IO	B7
1	IO	C8[1]
1	IO	D8[1]
1	IO_L17N_YY	A6
1	IO_VREF_1_L17P_YY	B6
1	IO_L18N_YY	C7
1	IO_L18P_YY	A4
1	IO	B5[1]
1	IO_L19N_YY	C6
1	IO_VREF_1_L19P_YY	D6[2]

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
1	IO	B4
1	IO	C5[1]
1	IO	A3[1]
1	IO_WRITE_L20N_YY	D5
1	IO_CS_L20P_YY	C4
2	IO_DOUT_BUSY_L21P_YY	E4
2	IO_DIN_D0_L21N_YY	D3
2	IO	C2[1]
2	IO	E3[1]
2	IO	F4
2	IO_VREF_2_L22P_YY	D2[2]
2	IO_L22N_YY	C1
2	IO	D1[1]
2	IO_L23P_YY	G4
2	IO_L23N_YY	F3
2	IO_VREF_2_L24P_Y	E2
2	IO_L24N_Y	F2
2	IO	G3[1]
2	IO	G2[1]
2	IO_L25P	F1
2	IO_L25N	J4
2	IO	H3
2	IO_VREF_2_L26P _Y	H2
2	IO_D1_L26N _Y	G1
2	IO_D2_L27P_YY	J3
2	IO_L27N_YY	J2
2	IO	K3[1]
2	IO_L28P	J1
2	IO_L28N	L4
2	IO	K2[1]
2	IO_L29P_YY	L3
2	IO_L29N_YY	L2
2	IO_VREF_2_L30P _Y	M4

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
7	IO_L165N_YY	P32	
7	IO_VREF_L165P_YY	P31	
7	IO_L166N_Y	P30	
7	IO_L166P_Y	P29	
7	IO_L167N_Y	M32	
7	IO_L167P_Y	N31	
7	IO_L168N_Y	N30	
7	IO_VREF_L168P_Y	L33	3
7	IO_L169N_Y	M31	
7	IO_L169P_Y	L32	
7	IO_L170N_Y	M30	
7	IO_L170P_Y	L31	
7	IO_L171N_YY	M29	
7	IO_L171P_YY	J33	
7	IO_L172N_YY	L30	
7	IO_VREF_L172P_YY	K31	
7	IO_L173N_Y	L29	
7	IO_L173P_Y	H33	
7	IO_L174N_Y	J31	
7	IO_VREF_L174P_Y	H32	4
7	IO_L175N_Y	K29	
7	IO_L175P_Y	H31	
7	IO_L176N_Y	J30	
7	IO_VREF_L176P_Y	G32	1
7	IO_L177N_YY	J29	
7	IO_VREF_L177P_YY	G31	
7	IO_L178N_Y	E33	
7	IO_L178P_Y	E32	
7	IO_L179N_Y	H29	
7	IO_L179P_Y	F31	
7	IO_L180N_Y	D32	
7	IO_VREF_L180P_Y	E31	
7	IO_L181N_Y	G29	
7	IO_L181P_Y	C33	
7	IO_L182N_Y	F30	

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
7	IO_VREF_L182P_Y	D31	3
2	CCLK	C4	
3	DONE	AJ5	
NA	DXN	AK29	
NA	DXP	AJ28	
NA	M0	AJ29	
NA	M1	AK30	
NA	M2	AN32	
NA	PROGRAM	AM1	
NA	TCK	E29	
NA	TDI	D5	
2	TDO	E6	
NA	TMS	B33	
NA	NC	C31	
NA	NC	AC2	
NA	NC	AK4	
NA	NC	AL3	
NA	VCCINT	A21	
NA	VCCINT	B12	
NA	VCCINT	B14	
NA	VCCINT	B18	
NA	VCCINT	B28	
NA	VCCINT	C22	
NA	VCCINT	C24	
NA	VCCINT	E9	
NA	VCCINT	E12	
NA	VCCINT	F2	
NA	VCCINT	H30	
NA	VCCINT	J1	
NA	VCCINT	K32	
NA	VCCINT	M3	
NA	VCCINT	N1	

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	1	C14	B14	2	-
19	1	A15	F12	2	-
20	1	C15	B15	√	-
21	1	E14	A16	√	VREF
22	1	C16	D14	2	-
23	1	A17	D15	2	-
24	1	A18	B17	√	VREF
25	1	C17	D16	√	-
26	1	A19	B18	√	VREF
27	1	C18	D17	√	-
28	1	C19	A20	√	CS
29	2	C21	D20	√	DIN, D0
30	2	C22	D21	√	-
31	2	D22	E21	√	VREF
32	2	E22	F18	√	-
33	2	F21	F19	√	VREF
34	2	F22	G19	2	-
35	2	G20	G18	1	-
36	2	H18	H22	2	D1, VREF
37	2	H20	H19	√	D2
38	2	H21	J19	√	-
39	2	J18	J20	√	-
40	2	K18	J21	2	-
41	2	K22	K21	1	VREF
42	2	K19	L22	2	-
43	2	L21	L18	√	-
44	2	L17	L20	√	-
45	3	M18	M20	√	-
46	3	M19	M17	2	-
47	3	N22	N21	2	VREF
48	3	N20	N18	√	-
49	3	N19	P21	√	-
50	3	P20	P19	√	-
51	3	P18	R21	√	D5
52	3	T22	R19	2	VREF

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
53	3	U22	R18	2	-
54	3	T21	V22	√	-
55	3	T20	U21	√	VREF
56	3	W22	T18	√	-
57	3	U19	U20	√	VREF
58	3	W21	AA22	√	-
59	3	Y21	V19	√	INIT
60	4	W18	AA20	√	-
61	4	Y18	V17	NA	-
62	4	AB20	W17	√	VREF
63	4	AA18	V16	NA	-
64	4	AB19	AB18	√	VREF
65	4	W16	AA17	1	-
66	4	Y16	V15	1	-
67	4	AB16	Y15	√	VREF
68	4	AA15	AB15	√	-
69	4	W15	Y14	1	-
70	4	V14	AA14	1	-
71	4	AB14	V13	NA	-
72	4	AA13	AB13	√	VREF
73	4	W13	AA12	2	-
74	4	Y12	V12	2	-
75	5	U12	AA11	NA	IO_LVDS_DLL
76	5	AB11	W11	1	-
77	5	V11	Y10	√	VREF
78	5	AB10	W10	√	-
79	5	V10	Y9	2	-
80	5	AB9	W9	2	-
81	5	V9	AA8	√	-
82	5	Y8	W8	√	VREF
83	5	W7	AA7	2	-
84	5	AB6	AA6	2	-
85	5	AB5	AA5	√	VREF
86	5	Y7	W6	√	-
87	5	AA4	Y6	√	VREF

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	P14
NA	GND	P13
NA	GND	P12
NA	GND	P11
NA	GND	P10
NA	GND	N2
NA	GND	N17
NA	GND	N16
NA	GND	N15
NA	GND	N14
NA	GND	N13
NA	GND	N12
NA	GND	N11
NA	GND	N10
NA	GND	M17
NA	GND	M16
NA	GND	M15
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	L17
NA	GND	L16
NA	GND	L15
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	K17
NA	GND	K16
NA	GND	K15
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	K10
NA	GND	J25
NA	GND	J2
NA	GND	E5
NA	GND	E22
NA	GND	D4
NA	GND	D23
NA	GND	C3
NA	GND	C24
NA	GND	B9
NA	GND	B25
NA	GND	B2
NA	GND	B18
NA	GND	B14
NA	GND	AF26
NA	GND	AF1
NA	GND	AE9
NA	GND	AE25
NA	GND	AE2
NA	GND	AE18
NA	GND	AE13
NA	GND	AD3
NA	GND	AD24
NA	GND	AC4
NA	GND	AC23
NA	GND	AB5
NA	GND	AB22
NA	GND	A26
NA	GND	A1

Notes:
1. NC in the XCV400E.
2. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	2	G24	H22	√	-
53	2	J21	G25	2	-
54	2	G26	J22	1	VREF
55	2	H24	J23	√	-
56	2	J24	K20	√	VREF
57	2	K22	K21	√	D2
58	2	H25	K23	√	-
59	2	L20	J26	2	-
60	2	K25	L22	1	-
61	2	L21	L23	1	-
62	2	M20	L24	1	-
63	2	M23	M22	√	D3
64	2	L26	M21	√	-
65	2	N19	M24	2	-
66	2	M26	N20	1	VREF
67	2	N24	N21	√	-
68	2	N23	N22	√	-
69	3	P21	P23	√	-
70	3	P22	R25	1	VREF
71	3	P19	P20	2	-
72	3	R21	R22	√	-
73	3	R24	R23	√	VREF
74	3	T24	R20	1	-
75	3	T22	U24	1	-
76	3	T23	U25	1	-
77	3	T21	U20	2	-
78	3	U22	V26	√	-
79	3	T20	U23	√	D5
80	3	V24	U21	√	VREF
81	3	V23	W24	√	-
82	3	V22	W26	1	VREF
83	3	Y25	V21	2	-
84	3	V20	AA26	√	-
85	3	Y24	W23	√	VREF

Table 21: **FG676 Differential Pin Pair Summary XCV400E, XCV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	3	AA24	Y23	1	-
87	3	AB26	W21	2	-
88	3	Y22	W22	1	VREF
89	3	AA23	AB24	2	-
90	3	W20	AC24	√	-
91	3	AB23	Y21	√	INIT
92	4	AC22	AD26	√	-
93	4	AD23	AA20	1	-
94	4	Y19	AC21	√	-
95	4	AD22	AB20	√	VREF
96	4	AE22	Y18	NA	-
97	4	AF22	AA19	NA	-
98	4	AD21	AB19	√	VREF
99	4	AC20	AA18	√	-
100	4	AC19	AD20	1	-
101	4	AF20	AB18	1	VREF
102	4	AD19	Y17	NA	-
103	4	AE19	AD18	NA	VREF
104	4	AF19	AA17	√	-
105	4	AC17	AB17	1	-
106	4	Y16	AE17	√	-
107	4	AF17	AA16	√	-
108	4	AD17	AB16	NA	-
109	4	AC16	AD16	√	-
110	4	AC15	Y15	√	VREF
111	4	AD15	AA15	√	-
112	4	W14	AB15	1	-
113	4	AF15	Y14	1	VREF
114	4	AD14	AB14	NA	-
115	5	AC14	AF13	NA	IO_LVDS_DLL
116	5	AA13	AF12	1	VREF
117	5	AC13	W13	1	-
118	5	AA12	AD12	√	-
119	5	AC12	AB12	√	VREF

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
3	IO_L97N	AA2
3	IO_L98P_YY	AC5
3	IO_L98N_YY	AB1
3	IO_D4_L99P_YY	AD3
3	IO_VREF_L99N_YY	AC1
3	IO_L100P_Y	AD1
3	IO_L100N_Y	AD4
3	IO_L101P	AD2
3	IO_L101N	AE3
3	IO_L102P_YY	AE1
3	IO_L102N_YY	AE4
3	IO_L103P_Y	AE2
3	IO_VREF_L103N_Y	AF3[1]
3	IO_L104P	AF4
3	IO_L104N	AF1
3	IO_L105P	AG3
3	IO_L105N	AF2
3	IO_L106P_Y	AG4
3	IO_L106N_Y	AG1
3	IO_L107P_YY	AH3
3	IO_D5_L107N_YY	AG2
3	IO_D6_L108P_YY	AH1
3	IO_VREF_L108N_YY	AJ2
3	IO_L109P	AH2
3	IO_L109N	AJ3
3	IO_L110P_YY	AJ1
3	IO_L110N_YY	AJ4
3	IO_L111P_YY	AK1
3	IO_VREF_L111N_YY	AK3
3	IO_L112P	AK2
3	IO_L112N	AK4
3	IO_L113P	AL1
3	IO_VREF_L113N	AL2[3]
3	IO_L114P_YY	AM1
3	IO_L114N_YY	AL3
3	IO_L115P_YY	AM2
3	IO_VREF_L115N_YY	AL4
3	IO_L116P_Y	AM3
3	IO_L116N_Y	AN1
3	IO_L117P	AM4
3	IO_L117N	AP1
3	IO_L118P_YY	AN2
3	IO_L118N_YY	AP2
3	IO_L119P_Y	AN3
3	IO_VREF_L119N_Y	AR1
3	IO_L120P	AN4
3	IO_L120N	AT1
3	IO_L121P	AR2
3	IO_VREF_L121N	AP4[1]
3	IO_L122P_Y	AT2
3	IO_L122N_Y	AR3
3	IO_D7_L123P_YY	AR4
3	IO_INIT_L123N_YY	AU2
4	GCK0	AW19
4	IO	AV3
4	IO_L124P_YY	AU4
4	IO_L124N_YY	AV5
4	IO_L125P_Y	AT6
4	IO_L125N_Y	AV4
4	IO_VREF_L126P_Y	AU6[1]
4	IO_L126N_Y	AW4
4	IO_L127P_YY	AT7
4	IO_L127N_YY	AW5
4	IO_VREF_L128P_YY	AU7
4	IO_L128N_YY	AV6
4	IO_L129P_Y	AT8
4	IO_L129N_Y	AW6
4	IO_L130P_Y	AU8
4	IO_L130N_Y	AV7
4	IO_L131P_YY	AT9
4	IO_L131N_YY	AW7

Table 23: **FG680 Differential Pin Pair Summary**
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	6	AP39	AP38	4	-
189	6	AN38	AN36	6	VREF
190	6	AN39	AN37	√	-
191	6	AM38	AM36	4	-
192	6	AL36	AM37	6	-
193	6	AL37	AM39	√	VREF
194	6	AK36	AL38	√	-
195	6	AK37	AL39	7	VREF
196	6	AJ36	AK38	4	-
197	6	AJ37	AK39	√	VREF
198	6	AH37	AJ38	√	-
199	6	AH38	AJ39	4	-
200	6	AG38	AH39	√	VREF
201	6	AG39	AG36	√	-
202	6	AF39	AG37	6	-
203	6	AE38	AF36	4	-
204	6	AF38	AF37	4	-
205	6	AE36	AE39	6	VREF
206	6	AE37	AD38	√	-
207	6	AD36	AD39	4	-
208	6	AC39	AC38	6	-
209	6	AB38	AD37	√	VREF
210	6	AB39	AC35	√	-
211	6	AA38	AC36	7	-
212	6	AA39	AC37	4	-
213	6	Y38	AB35	√	VREF
214	6	Y39	AB36	√	-
215	6	AA36	AB37	4	VREF
216	7	W38	AA37	√	-
217	7	V39	W37	4	VREF
218	7	U39	W36	√	-
219	7	U38	V38	√	VREF
220	7	T39	V37	4	-
221	7	T38	V36	7	-

Table 23: **FG680 Differential Pin Pair Summary**
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	7	R39	V35	√	-
223	7	U36	U37	√	VREF
224	7	U35	R38	6	-
225	7	T37	P39	4	-
226	7	T36	P38	√	-
227	7	N38	N39	6	VREF
228	7	M39	R37	4	-
229	7	M38	R36	4	-
230	7	L39	P37	6	-
231	7	N37	P36	√	-
232	7	N36	L38	√	VREF
233	7	M37	K39	4	-
234	7	L37	K38	√	-
235	7	L36	J39	√	VREF
236	7	K37	J38	4	-
237	7	K36	H39	√	VREF
238	7	J37	H38	√	-
239	7	G38	G39	√	VREF
240	7	F39	J36	6	-
241	7	F38	H37	4	-
242	7	E39	H36	√	-
243	7	E38	G37	6	VREF
244	7	D39	G36	4	-
245	7	F36	D38	4	VREF
246	7	E37	D37	6	-

Notes:
1. AO in the XCV1000E, 1600E, 2000E.
2. AO in the XCV600E, 1000E, 1600E.
3. AO in the XCV600E, 1000E.
4. AO in the XCV1000E, 1600E.
5. AO in the XCV1000E, 2000E.
6. AO in the XCV600E, 1000E, 2000E.
7. AO in the XCV1000E.
8. AO in the XCV2000E.

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
1	IO_L57N_Y	D9
1	IO_VREF_L57P_Y	A12[2]
1	IO_L58N_Y	E9
1	IO_L58P_Y	C12
1	IO_L59N_YY	B12
1	IO_VREF_L59P_YY	D8
1	IO_L60N_YY	A11
1	IO_L60P_YY	E8
1	IO_L61N_Y	C7
1	IO_L61P_Y	A10
1	IO_L62N_Y	C6
1	IO_L62P_Y	B10
1	IO_L63N_YY	A9
1	IO_VREF_L63P_YY	B9
1	IO_L64N_YY	A8
1	IO_L64P_YY	E7
1	IO_L65N_Y	B8
1	IO_L65P_Y	C5
1	IO_L66N_Y	A7
1	IO_VREF_L66P_Y	A6
1	IO_L67N_Y	B7
1	IO_L67P_Y	D6
1	IO_L68N_Y	A5
1	IO_L68P_Y	C4
1	IO_WRITE_L69N_YY	B6
1	IO_CS_L69P_YY	E6
2	IO	H2
2	IO	H3
2	IO	J1
2	IO	K5
2	IO	M2
2	IO	N1
2	IO	R5
2	IO	U1
2	IO	U4
2	IO	W3
2	IO	Y3
2	IO	AA3
2	IO_DOUT_BUSY_L70P_YY	F5
2	IO_DIN_D0_L70N_YY	D2
2	IO_L71P_Y	E4
2	IO_L71N_Y	E2
2	IO_L72P_Y	D3
2	IO_L72N_Y	F2
2	IO_VREF_L73P_Y	E1
2	IO_L73N_Y	F4
2	IO_L74P	G2
2	IO_L74N	E3
2	IO_L75P_Y	F1
2	IO_L75N_Y	G5
2	IO_VREF_L76P_Y	G1
2	IO_L76N_Y	F3
2	IO_L77P_YY	G4
2	IO_L77N_YY	H1
2	IO_L78P_Y	J2
2	IO_L78N_Y	G3
2	IO_L79P_Y	H5
2	IO_L79N_Y	K2
2	IO_VREF_L80P_YY	H4
2	IO_L80N_YY	K1
2	IO_L81P_YY	L2
2	IO_L81N_YY	L3
2	IO_VREF_L82P_Y	L1[2]
2	IO_L82N_Y	J5
2	IO_L83P_Y	J4
2	IO_L83N_Y	M3
2	IO_VREF_L84P_YY	J3
2	IO_L84N_YY	M1
2	IO_L85P_YY	N2
2	IO_L85N_YY	K4
2	IO_L86P_Y	N3
2	IO_L86N_Y	K3
2	IO_VREF_L87P_YY	L5

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40[2]
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
7	IO_L275N_Y	G38
7	IO_VREF_L275P_Y	G42
7	IO_L276N_Y	G41
7	IO_L276P_Y	F40
7	IO_L277N	F42
7	IO_L277P	F41
7	IO_L278N_Y	F39
7	IO_VREF_L278P_Y	E42
7	IO_L279N_Y	E40
7	IO_L279P_Y	E41
7	IO_L280N_Y	E39
7	IO_L280P_Y	D41
2	CCLK	B4
3	DONE	AW2
NA	DXN	BA38
NA	DXP	AW38
NA	M0	AW41
NA	M1	AV37
NA	M2	BA39
NA	PROGRAM	AV2
NA	TCK	B38
NA	TDI	B5
2	TDO	D5
NA	TMS	B39
NA	VCCINT	F9
NA	VCCINT	F10
NA	VCCINT	F17
NA	VCCINT	F18
NA	VCCINT	F25
NA	VCCINT	F26
NA	VCCINT	F33
NA	VCCINT	F34
NA	VCCINT	J6
NA	VCCINT	J37
NA	VCCINT	K6

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCINT	K37
NA	VCCINT	T6
NA	VCCINT	T37
NA	VCCINT	U6
NA	VCCINT	U37
NA	VCCINT	V6
NA	VCCINT	V37
NA	VCCINT	AE6
NA	VCCINT	AE37
NA	VCCINT	AF6
NA	VCCINT	AF37
NA	VCCINT	AG6
NA	VCCINT	AG37
NA	VCCINT	AN6
NA	VCCINT	AN37
NA	VCCINT	AP6
NA	VCCINT	AP37
NA	VCCINT	AU9
NA	VCCINT	AU10
NA	VCCINT	AU17
NA	VCCINT	AU18
NA	VCCINT	AU25
NA	VCCINT	AU26
NA	VCCINT	AU33
NA	VCCINT	AU34
NA	VCCO_0	F23
NA	VCCO_0	F24
NA	VCCO_0	F28
NA	VCCO_0	F29
NA	VCCO_0	F31
NA	VCCO_0	F32
NA	VCCO_0	F35
NA	VCCO_0	F36
NA	VCCO_1	F11
NA	VCCO_1	F12
NA	VCCO_1	F14

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_1	F15
NA	VCCO_1	F19
NA	VCCO_1	F20
NA	VCCO_1	F7
NA	VCCO_1	F8
NA	VCCO_2	G6
NA	VCCO_2	H6
NA	VCCO_2	L6
NA	VCCO_2	M6
NA	VCCO_2	P6
NA	VCCO_2	R6
NA	VCCO_2	W6
NA	VCCO_2	Y6
NA	VCCO_3	AC6
NA	VCCO_3	AD6
NA	VCCO_3	AH6
NA	VCCO_3	AJ6
NA	VCCO_3	AL6
NA	VCCO_3	AM6
NA	VCCO_3	AR6
NA	VCCO_3	AT6
NA	VCCO_4	AU11
NA	VCCO_4	AU12
NA	VCCO_4	AU14
NA	VCCO_4	AU15
NA	VCCO_4	AU19
NA	VCCO_4	AU20
NA	VCCO_4	AU7
NA	VCCO_4	AU8
NA	VCCO_5	AU23
NA	VCCO_5	AU24
NA	VCCO_5	AU28
NA	VCCO_5	AU29
NA	VCCO_5	AU31
NA	VCCO_5	AU32
NA	VCCO_5	AU35
NA	VCCO_5	AU36

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_6	AC37
NA	VCCO_6	AD37
NA	VCCO_6	AH37
NA	VCCO_6	AJ37
NA	VCCO_6	AL37
NA	VCCO_6	AM37
NA	VCCO_6	AR37
NA	VCCO_6	AT37
NA	VCCO_7	G37
NA	VCCO_7	H37
NA	VCCO_7	L37
NA	VCCO_7	M37
NA	VCCO_7	P37
NA	VCCO_7	R37
NA	VCCO_7	W37
NA	VCCO_7	Y37
NA	GND	N6
NA	GND	N5
NA	GND	N38
NA	GND	N37
NA	GND	F6
NA	GND	F37
NA	GND	F30
NA	GND	F22
NA	GND	F21
NA	GND	F13
NA	GND	E5
NA	GND	E38
NA	GND	E30
NA	GND	E22
NA	GND	E21
NA	GND	E13
NA	GND	D42
NA	GND	D4
NA	GND	D39
NA	GND	D1

FG900 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	C15	A15	NA	IO_DLL_ 34N
2	1	E15	E16	NA	IO_DLL_ 34P
1	5	AK16	AH16	NA	IO_DLL_ 177N
0	4	AJ16	AF16	NA	IO_DLL_ 177P
IO LVDS Total Pairs: 283, Asynchronous Output Pairs: 168					
0	0	F7	C4	4	-
1	0	G8	D5	2	-
2	0	H9	A3	2	VREF
3	0	J10	B4	2	-
4	0	D6	A4	√	-
5	0	B5	E7	√	VREF
6	0	F8	A5	1	-
7	0	N11	D7	1	-
8	0	E8	G9	√	-
9	0	J11	A6	√	VREF
10	0	B7	C7	2	-
11	0	H10	C8	2	-
12	0	F10	G10	√	-
13	0	H11	A8	√	VREF
14	0	C9	D9	NA	-
15	0	J12	B9	4	-
16	0	A9	E10	NA	VREF
17	0	B10	G11	NA	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	C10	H12	4	-
19	0	F11	H13	2	-
20	0	D11	E11	2	-
21	0	G12	B11	2	-
22	0	C11	F12	√	-
23	0	D12	A10	√	VREF
24	0	A11	E12	1	-
25	0	B12	G13	1	-
26	0	K13	A12	√	-
27	0	B13	F13	√	VREF
28	0	E13	G14	2	-
29	0	B14	D14	2	-
30	0	J14	A14	√	-
31	0	J15	K14	√	VREF
32	0	H15	B15	NA	-
33	0	D15	F15	√	VREF
34	1	E16	A15	NA	IO_ LVDS_DLL
35	1	F16	B16	4	VREF
36	1	H16	A16	4	-
37	1	K15	C16	√	VREF
38	1	G16	K16	√	-
39	1	E17	A17	2	-
40	1	C17	F17	2	-
41	1	A18	E18	√	VREF
42	1	A19	D18	√	-
43	1	G18	B19	1	-
44	1	H18	D19	1	-
45	1	F19	F18	√	VREF
46	1	K17	B20	√	-
47	1	A20	D20	2	-
48	1	C20	G19	2	-
49	1	E20	K18	2	-
50	1	D21	B21	4	-
51	1	A21	F20	√	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
71	1	A27	G24	3200 2000 1000	-
72	1	G25	B27	3200 1600	-
73	1	C27	E26	3200 2600 2000 1600 1000	VREF
74	1	B28	J24	3200 2600 2000 1600 1000	-
75	1	H25	K24	3200 2600	-
76	1	F26	D27	3200 1000	-
77	1	C28	G26	3200 1000	-
78	1	J25	E27	2000 1600	-
79	1	H26	A30	3200 2600 2000 1600 1000	VREF
80	1	B29	G27	3200 2600 2000 1600 1000	-
81	1	C29	F27	3200 2600 1000	-
82	1	F28	E28	3200 2000 1000	VREF
83	1	B30	L25	3200 2000 1000	-
84	1	E29	B31	3200 1600 1000	-
85	1	D30	A31	3200 2600 2000 1600 1000	CS
86	2	D32	J27	3200 2600 2000 1600 1000	DIN, D0
87	2	E31	F30	3200 2600 2000	-
88	2	G29	F32	2600 2000 1000	-
89	2	E32	G30	3200 2600 1600 1000	VREF
90	2	M25	G31	2600 1600	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
91	2	L26	D33	3200 2600 1600 1000	-
92	2	D34	H29	2600 2000 1000	VREF
93	2	J28	E33	3200 2600 2000 1600	-
94	2	H28	H30	3200 2600 2000 1600 1000	-
95	2	H32	K28	3200 2600 1600 1000	-
96	2	L27	F33	3200 2600 2000	-
97	2	M26	E34	2600 2000 1000	-
98	2	H31	G32	3200 2600 2000 1600 1000	VREF
99	2	N25	J31	2000 1600	-
100	2	J30	G33	3200 2600 2000 1600 1000	-
101	2	H34	J29	2600 1000	VREF
102	2	M27	H33	3200 2600 1600	-
103	2	K29	J34	3200 2600 1600 1000	-
104	2	L29	J33	3200 2600 2000 1600 1000	VREF
105	2	M28	K34	3200 2600 2000 1600 1000	-
106	2	N27	L34	3200 1600 1000	-
107	2	K33	P26	2000 1600 1000	D1
108	2	R25	M34	3200 2600 2000	-
109	2	L31	L33	2000 1000	-
110	2	P27	M33	3200 2600 1600 1000	-